

Product / Process Change Notification



N° 2018-059-A

!! correction !!

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Several Changes affecting Gen6.2 IGBT in TO247 packages

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **12 August 2020**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:
“**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

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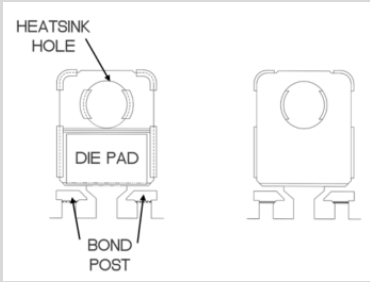
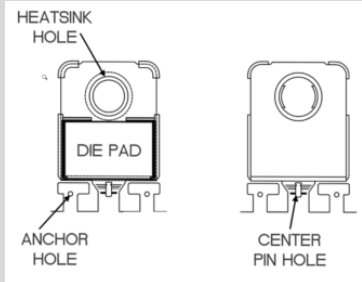
► **Products affected:**

Please refer to attached affected product list 1_cip18059_A

► **Detailed Change Information:**

Subject: Several Changes affecting Gen6.2 IGBT in TO247 packages

Reason: The wafer production of the affected products will be transferred to Vanguard International Semiconductor and Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia according to the global Infineon production strategy.

Description:	<u>Old</u>	<u>New</u>
Wafer Site FEOL	<ul style="list-style-type: none"> Infineon Technologies Americas Corp., Temecula, United States 	<ul style="list-style-type: none"> Vanguard International Semiconductor
Wafer Site BEOL	<ul style="list-style-type: none"> Infineon Technologies Americas Corp., Temecula, United States 	<ul style="list-style-type: none"> Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia
Wafer Diameter	<ul style="list-style-type: none"> 6 inch 	<ul style="list-style-type: none"> 8 inch
Assembly Changes Leadframe	<ul style="list-style-type: none"> Mold locking features 	<ul style="list-style-type: none"> Updated Mold locking features 
Final Test Location	<ul style="list-style-type: none"> Infineon Technologies Americas Corp., Temecula, United States 	<ul style="list-style-type: none"> Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia Infineon Technologies Americas Corp., Temecula, United States

► **Product Identification:**

Traceability assured via date code.
No change in SP ordering number

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► Impact of Change:

Based on the qualification performed, Infineon does not see any negative impact on quality, function and reliability

De Qu Ma Ids; SEM-PW-02, SEM-PW-06, SEM-PW-07, SEM-PW-08, SEM-PA-03, SEM-PW-13, SEM-TF-01

► Attachments:

Affected product list 1_cip18059_A

► Time Schedule:

- | | |
|-------------------------------|---|
| ■ Final qualification report: | Available upon request |
| ■ First samples available: | Upon request |
| ■ Intended start of delivery: | 12-January-2021 or earlier upon customer approval |

If you have any questions, please do not hesitate to contact your local Sales office.

PCN N° 18-059A

Title

Change of Wafer Production from Infineon Technologies (Temecula) to Vanguard International Semiconductor and Infineon Technologies (Kulim) and leadframe change for Gen6.2 IGBT in TO247 packages



Sales name	SP number	OPN	Package
AUIRGP4062D	SP001511212	AUIRGP4062D	PG-TO247-3-904
AUIRGP4062D-E	SP001511902	AUIRGP4062D-E	PG-TO247-3-904
AUIRGP4063D	SP001512458	AUIRGP4063D	PG-TO247-3-904
AUIRGP4063D-E	SP001512018	AUIRGP4063D-E	PG-TO247-3-904
AUXHKGP4062D-E	SP001662772	AUXHKGP4062D-E	PG-TO247-3-904
AUXVNGP4062D-E	SP001511846	AUXVNGP4062D-E	PG-TO247-3-904